Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4180	(361/719,720,707,704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 09:25
L2	1286	(361/719).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 09:25
L3	31915156	I2 @pd< "20030429"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 09:26
L4	814	l2 and @pd< "20030429"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 09:26
L5	198	I4 and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 09:29
L6	2	("5218516").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 12:28
L7	26560	intel .as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:28
L8	941	(heat adj sink) same magnet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:29

		10 and 17	LIC DCDUD	OB	ON	2005/12/01 12:20
L9	5	18 and 17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 12:29
S1	195	(361/721).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/01 09:25
S2	25	("3348148" "4656559" "4858071" "4916575" "5060112").PN. OR ("5218516").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/30 15:10
S3	21	"5218516"	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/30 15:10
S4	2	("5218516").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 15:32
S5	0	(361/386).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 15:35
S6	4359	(electronic with module) and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:36
S7	339	S6 and heat adj conduction	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:37
S8	93	S7 and ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:38

S9	6177	(heat adj sink) and (substrate or pcb) and ground and (electronic or chip or device)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:39
S10	491	((heat adj sink) and (substrate or pcb)) with ground and (electronic or chip or device)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:04
S11	10	S10 and (copper adj heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:05
S12	90	S10 and (copper with (heat adj sink))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:14
S13	31226	(fin and fans)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:18
S14	1639	(361/695).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:18
S15	968	S14 and @pd< "20030101"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:18
S16	246	S15 and fan and fin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 16:19